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- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
 ESD Protection Exceeds 2000 V Per
- MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Small-Outline (D), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

D, DGV, OR PW PACKAGE (TOP VIEW)									
1A [1B [1Y [2A [2B [2Y [GND [2 3 4 5	U 14 13 12 11 10 9 8] V _{CC}] 4B] 4A] 4Y] 3B] 3A] 3Y						

description

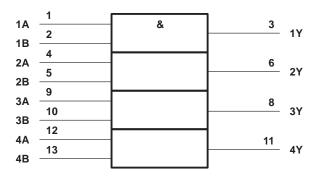
This quadruple 2-input positive-AND gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The device performs the Boolean function $Y = A \bullet B$ or $Y = \overline{\overline{A} + \overline{B}}$ in positive logic.

The SN74ALVC08 is characterized for operation from -40°C to 85°C.

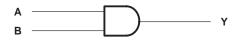
FUNCTION TABLE (each gate)							
INPUTS OUTPUT							
Α	В	ВҮ					
Н	Н	Н					
L	Х	L					
Х	L	L					

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each gate (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Notes 1 and 2) Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$) Continuous output current, I_O Continuous current through V_{CC} or GND	$\begin{array}{c} -0.5 \ \text{V to } 4.6 \ \text{V} \\ -0.5 \ \text{V to } \ \text{V}_{CC} + 0.5 \ \text{V} \\ -50 \ \text{mA} \\ -50 \ \text{mA} \\ \pm 50 \ \text{mA} \\ \pm 100 \ \text{mA} \end{array}$
Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 3): D package	
DGV package	182°C/W
PW package Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 4.6 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		1.65	3.6	V
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
VIH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	2		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
VI	Input voltage		0	VCC	V
Vo	Output voltage		0	VCC	V
	High-level output current	V _{CC} = 1.65 V		-4	
la.		V _{CC} = 2.3 V		-12	mA
ЮН		$V_{CC} = 2.7 V$		-12	
		$V_{CC} = 3 V$		-24	
		V _{CC} = 1.65 V		4	
la.	Low-level output current	V _{CC} = 2.3 V	12]
IOL		$V_{CC} = 2.7 V$		12	mA
	V _{CC} = 3 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	5	ns/V
Тд	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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PARAMETER	TEST CONDITI	ONS	Vcc	MIN	түр†	MAX	UNIT	
	I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2			
	I _{OH} = -4 mA		1.65 V	1.2				
	I _{OH} = -6 mA		2.3 V	2				
VOH			2.3 V	1.7			V	
	I _{OH} = -12 mA		2.7 V	2.2				
			3 V	2.4				
	I _{OH} = -24 mA	3 V	2					
	I _{OL} = 100 μA		1.65 V to 3.6 V			0.2		
	I _{OL} = 4 mA		1.65 V			0.45		
	I _{OL} = 6 mA		2.3 V			0.4	v	
VOL	1	2.3 V			0.7	v		
	I _{OL} = 12 mA		2.7 V			0.4		
	I _{OL} = 24 mA		3 V			0.55		
l	$V_I = V_{CC} \text{ or } GND$		3.6 V			±5	μA	
ICC	$V_I = V_{CC}$ or GND, $I_O =$	= 0	3.6 V			10	μA	
ΔICC	One input at V _{CC} – 0.6 V, Oth	er inputs at V _{CC} or GND	3 V to 3.6 V			750	μA	
Ci	$V_I = V_{CC}$ or GND		3.3 V		4.5		pF	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

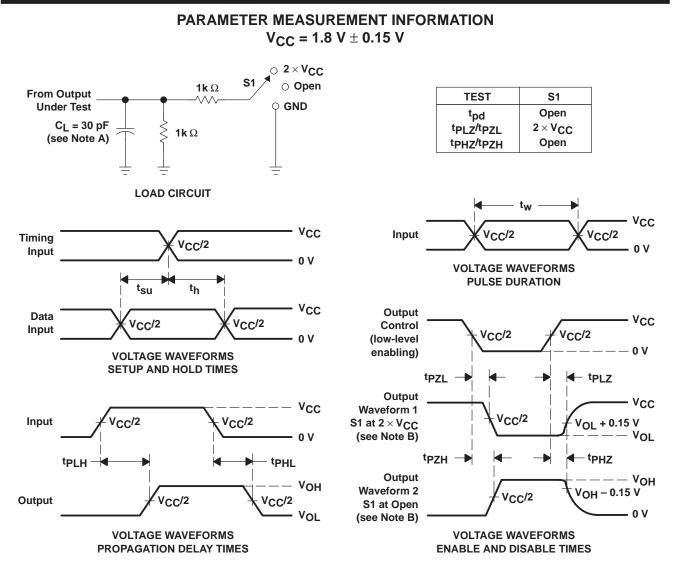
PARAMETER	FROM (INPUT) (C	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		(001101)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	A or B	Y	1.2	5.3	1	3.2		3	1.2	2.9	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS		V _{CC} = 1.8 V ± 0.15 V	$\begin{array}{c} \text{V}_{\text{CC}} = 2.5 \text{ V} \\ \pm 0.2 \text{ V} \end{array}$	V_{CC} = 3.3 V ± 0.3 V	UNIT
				TYP	TYP	TYP	
C _{pd}	Power dissipation capacitance per gate	C _L = 0,	f = 10 MHz	24	25	26	pF



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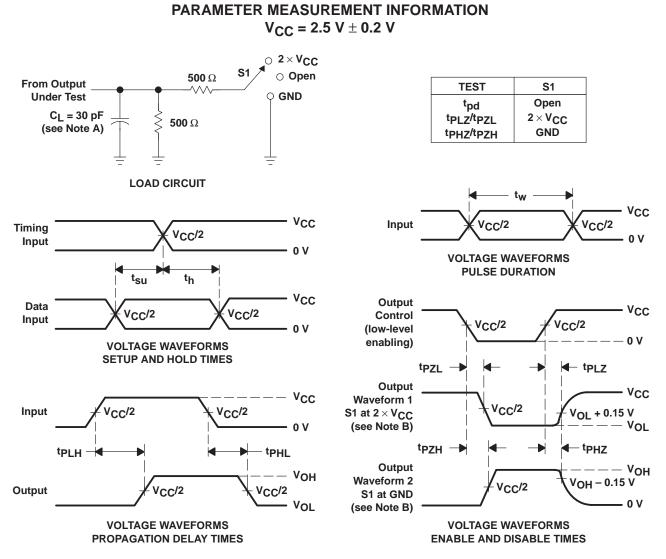


- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - C. An input pulses are supplied by generators having the following characteristics. FRR \ge 10 Min2, 20 = 50.22, tr \ge 21s, tr \ge 2
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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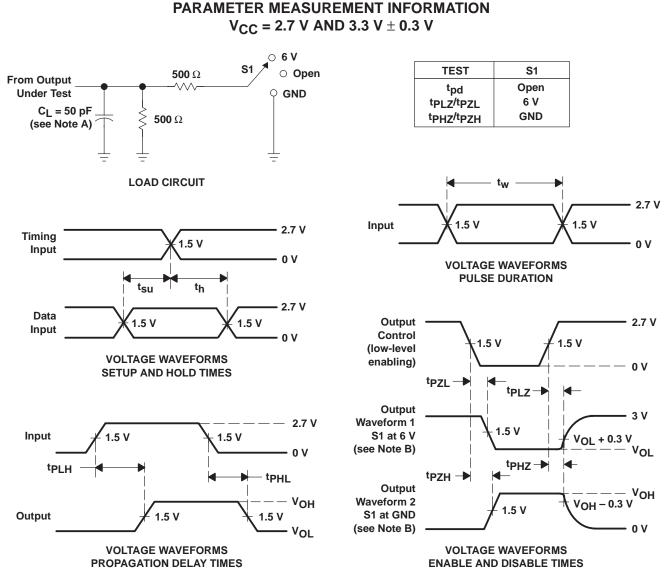


- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - D. The outputs are measured one at a time with one tra
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tPLH and tPHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

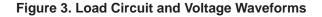


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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .





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